

# **DSF8045SK**

# **Fast Recovery Diode**

DS4146-8 July 2014 (LN31792)

### **FEATURES**

- Double Side Cooling
- High Surge Capability
- Low Recovery Charge

# **APPLICATIONS**

Antiparallel and FWD for GTO

### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages V <sub>RRM</sub> V	Conditions
DSF8045SK45	4500	
DSF8045SK44	4400	$V_{RSM} = V_{RRM} + 100V$
DSF8045SK43	4300	
DSF8045SK42	4200	
DSF8045SK41	4100	
DSF8045SK40	4000	

Lower voltage grades available.

### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

**DSF8045SK43** for a 4300V device

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order

### **KEY PARAMETERS**

$V_{RRM}$	4500V
I <sub>F(AV)</sub>	430A
I <sub>FSM</sub>	3500A
$Q_r$	440μC
t <sub>rr</sub>	3. <b>07</b> μs

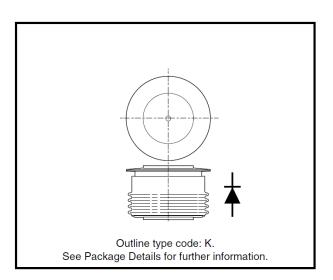


Fig. 1 Package outline

# **CURRENT RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units		
Double Si	Double Side Cooled					
$I_{F(AV)}$	Mean forward current	Half wave resistive load T <sub>case</sub> = 65°C	430	А		
I <sub>F(RMS)</sub>	RMS value	T <sub>case</sub> = 65°C -	680	Α		
I <sub>F</sub>	Continuous (direct) on-state current	T <sub>case</sub> = 65°C -	600	Α		
Single Side Cooled (Anode side)						
$I_{F(AV)}$	Mean forward current	Half wave resistive load T <sub>case</sub> = 65°C -	285	А		
I <sub>F(RMS)</sub>	RMS value	T <sub>case</sub> = 65°C	445	Α		
I <sub>F</sub>	Continuous (direct) on-state current	T <sub>case</sub> = 65°C	380	Α		

# **SURGE RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
I <sub>FSM</sub>	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 150$ °C	2.8	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$V_R = 50\% V_{RRM}$	61.25	kA <sup>2</sup> s
I <sub>FSM</sub>	Surge (non-repetitive) on-state current	10ms half sine, T <sub>case</sub> = 150°C	3.5	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$V_R = 0$	39.2	kA <sup>2</sup> s

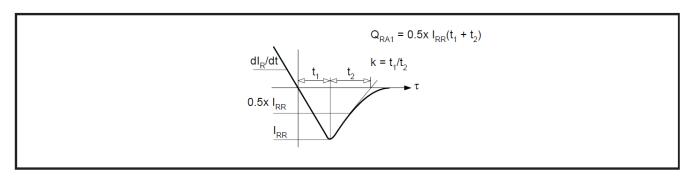
# THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance – junction to case	Double side cooled	DC	-	0.048	°C/W
		Single side cooled	Anode DC	-	0.09	°C/W
			Cathode DC	-	0.103	°C/W
R <sub>th(c-h)</sub>	Thermal resistance – case to heatsink	Clamping force 8kN	Double side	-	0.01	°C/W
		(with mounting compound)	Single side	-	0.02	°C/W
T <sub>vj</sub>	Virtual junction temperature	On-state (conducting)		-	150	°C
		Reverse (blocking)		-	150	°C
T <sub>stg</sub>	Storage temperature range			-55	175	°C
F <sub>m</sub>	Clamping force			7.0	9.0	kN

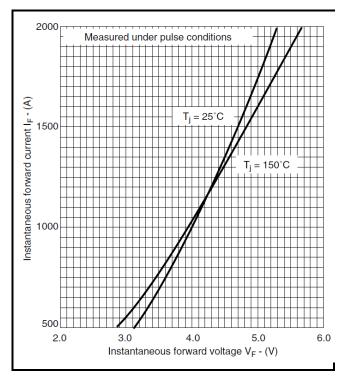
# **CHARACTERISTICS**

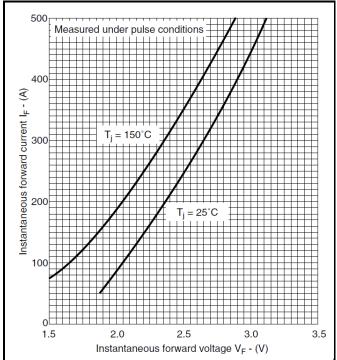
Symbol	Parameter	Test Conditions	Тур.	Max.	Units
$V_{FM}$	Forward voltage	At 1000A peak, T <sub>case</sub> = 25°C	-	4.0	V
I <sub>RM</sub>	Peak reverse current	At V <sub>DRM</sub> , T <sub>case</sub> = 150°C	-	50	mA
t <sub>rr</sub>	Reverse recovery time			3.07	μS
Qs	Total stored charge	$I_F = 1000A$ , $dI_{RR}/dt = 100A/\mu s$ $T_{case} = 150$ °C, $V_R = 100V$	-	440	μC
I <sub>rr</sub>	Peak reverse recovery current			240	Α
K	Softness Factor		-	-	-
V <sub>TO</sub>	Threshold voltage	At T <sub>vj</sub> = 150°C	-	1.7	V
r <sub>T</sub>	Slope resistance	At T <sub>vj</sub> =150°C	-	2.1	mΩ
$V_{FRM}$	Forward recovery voltage	Di/dt = 1000A/us, T <sub>j</sub> = 125°C		300	V

# DEFINITION OF K FACTOR AND $\mathbf{Q}_{\text{RA1}}$



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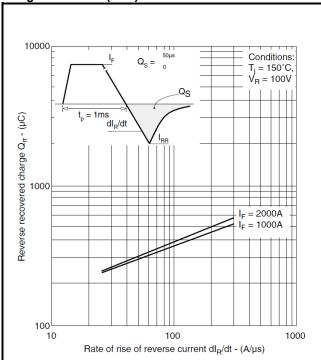


Fig.4 Recovered charge

Fig.3 Maximum (limit) on-state characteristics

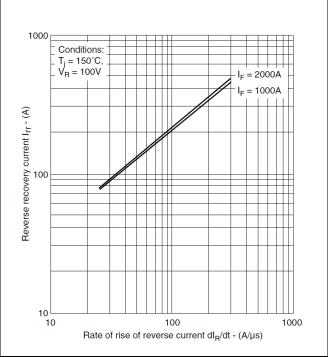


Fig.5 Typical reverse recovery current

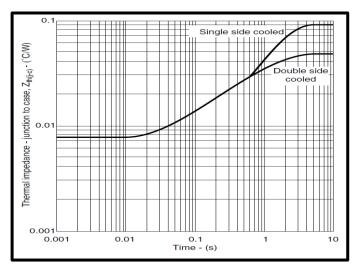


Fig.6 Maximum (limit) transient thermal impedance- junction to case

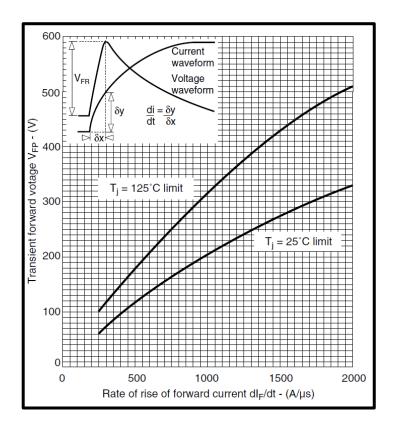
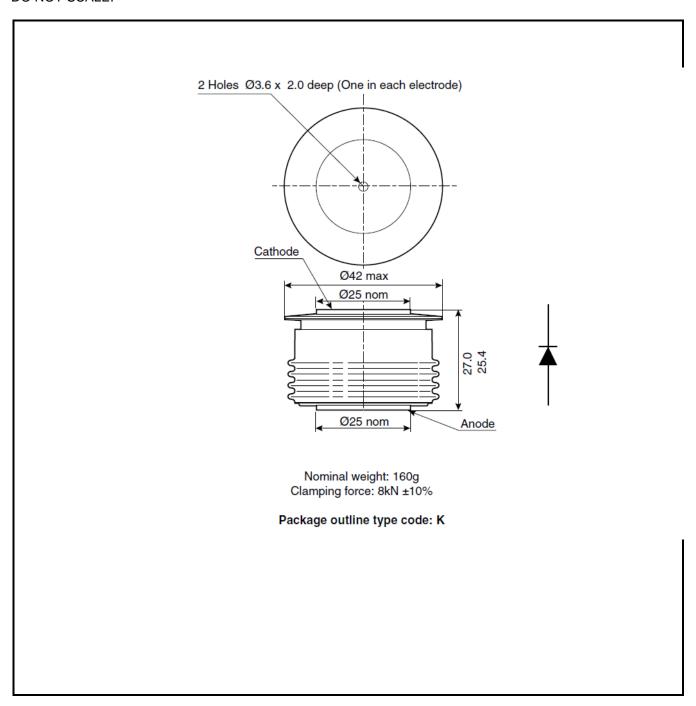


Fig.7 Transient forward voltage

# **PACKAGE DETAILS**

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



**Note:** Some packages may be supplied with gate and or tags.

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